The New Kid on the Timing Frontier: Characterising a Novel Timing the DESY II Test Beam Facility Characterising a Novel Timing and Triggering Plane for use with the EUDET Telescopes at

Arianna Wintle on behalf of the TelePix2 Team, Detector R&D Retreat 19/01/24

> **EXZELLENZCLUSTER** QUANTUM UNIVERSE















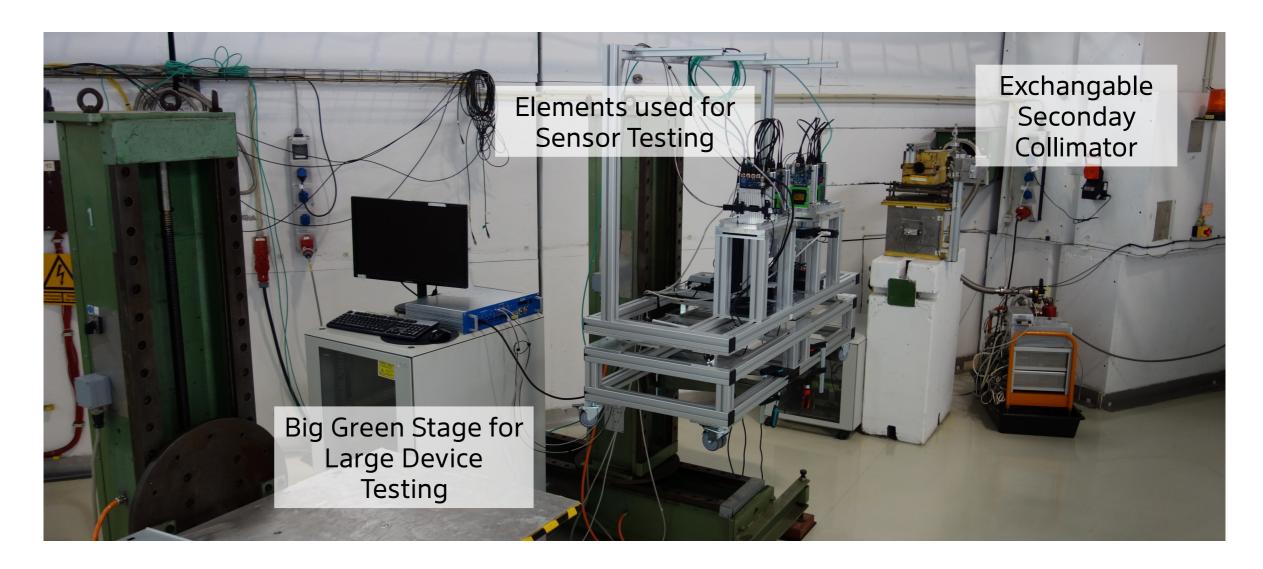
The DESYII Test Beam Facility



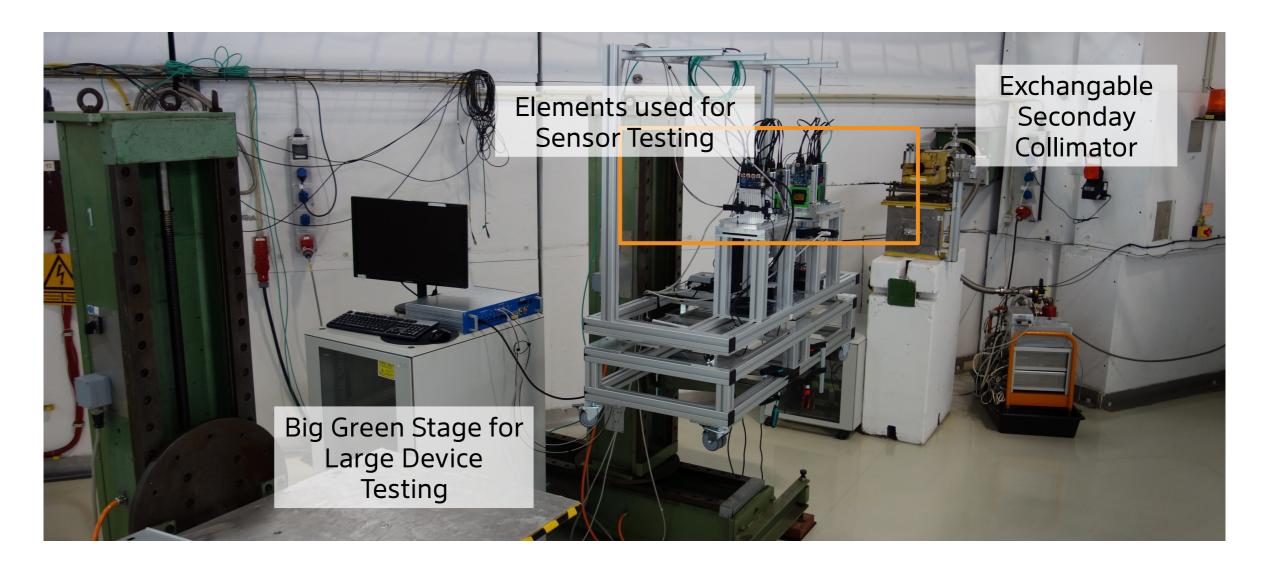
Three independent beamlines at the DESY II synchrotron

- → Typically used for detector R&D for characterisation
- \rightarrow Offers e^- or e^+ beam with user selectable momentum from 1-6 GeV/c
- → Shutter and primary collimator remote controllable
- → Exchangeable fixed size secondary collimator

Inside the Test Beam Area



Inside the Test Beam Area



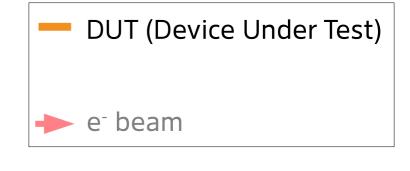
For Sensor Characterisation

DUT (Device Under Test)

Range of different sizes and operating conditions

Parameters to test:

- Efficiency
- Time Resolution & Spatial Resolution
- Behavior under a magnetic field

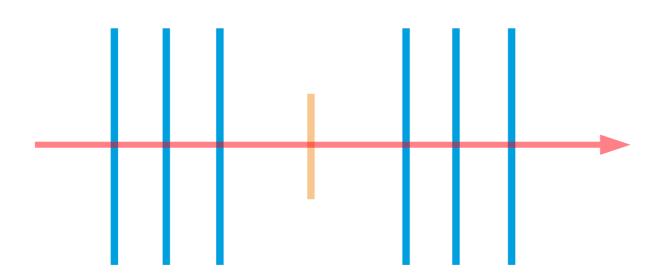


For Sensor Characterisation

Telescope

Multiple sensor planes Allow precise track reconstruction At DESY II Test Beam Facility two types with two different readout times:

Mimosa (~ 230 μs) & Adenium (~ 10 μs)

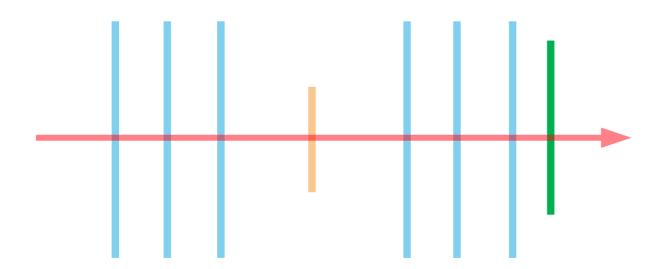


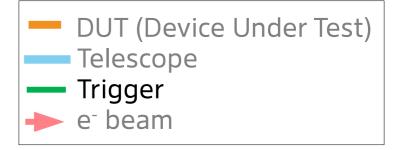


For Sensor Characterisation

Trigger

- Tag the presence of particles
- Important for reducing noise (event based readout)

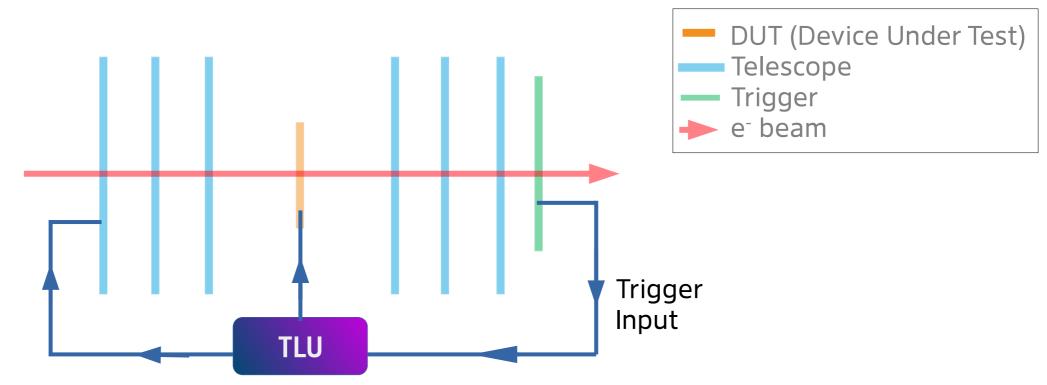




For Sensor Characterisation

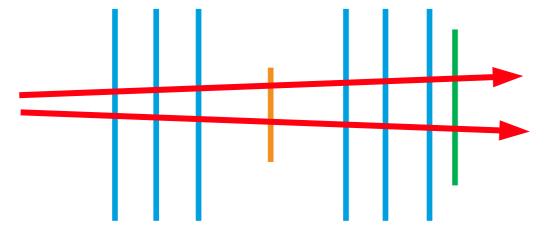
Trigger Logic Unit

- Trigger on an arbitrary logical combination of 6 triggering inputs
- Synchronisation of multiple devices: exchange trigger ID or common clock and reset





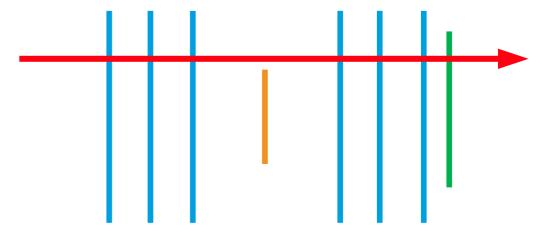
Slow telescope readout & high particle rates



Multiple tracks within one readout

→ Impossible to associate which
track belongs to which trigger

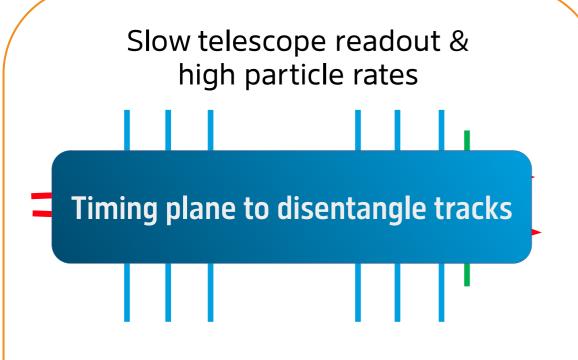
Mismatch in trigger and DUT size



Trigger on uninteresting events

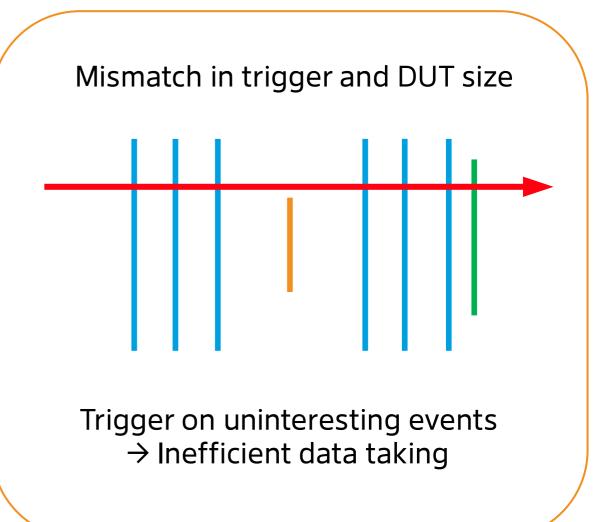
→ Inefficient data taking



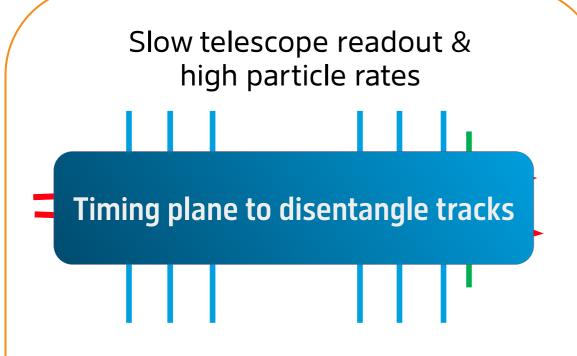


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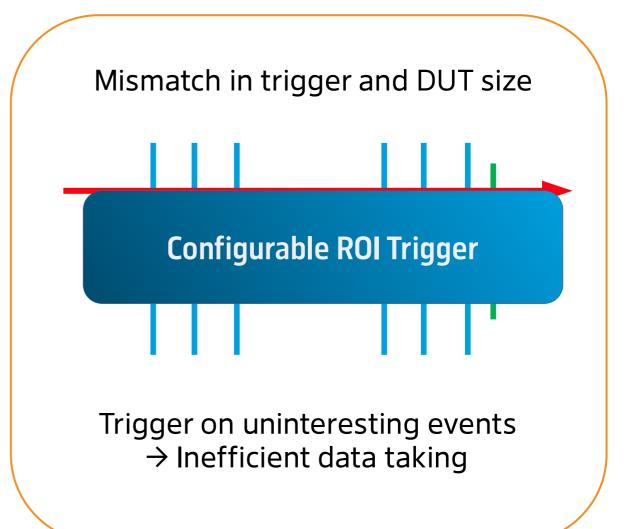


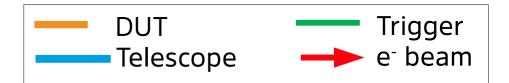


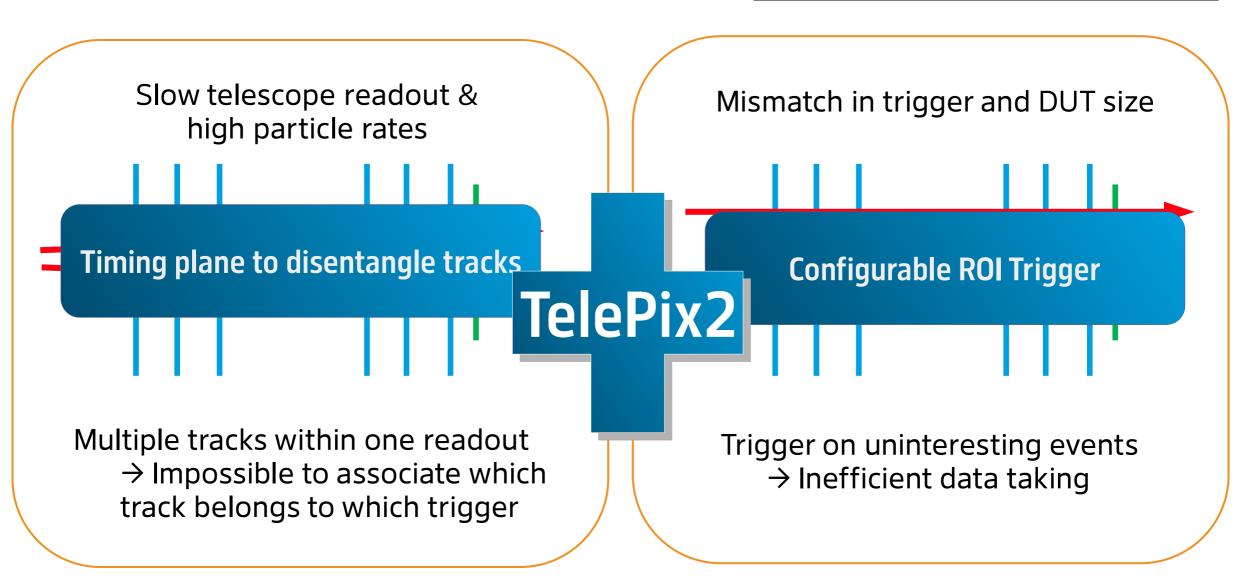


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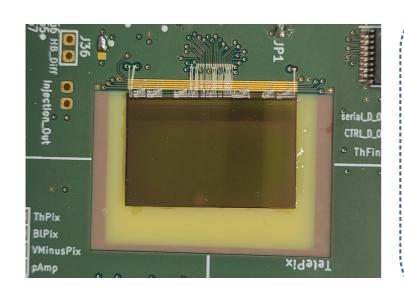
TelePix2

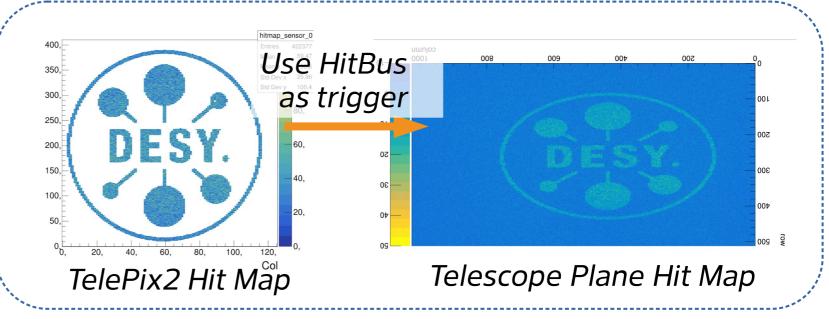
Key Features

- HVMAPS sensor with a fine timestamp (4 ns)
- Fast output for a user-configurable ROI trigger (HitBus)
- A low material budget (0.0011 from 100 µm silicon)

Pixel Size: 165 x 25 μm *Columns x Row*: 120 x 400

Chip size: 20.015 x 13.130 mm





Work in Progress



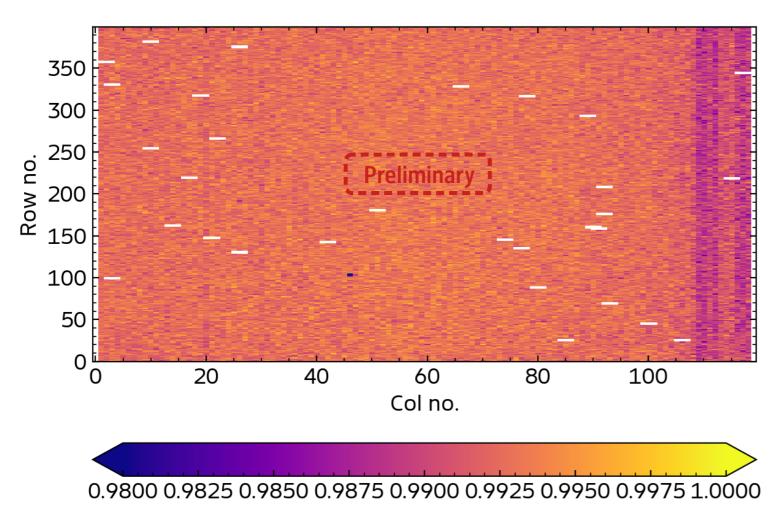
All the following results are preliminary, the analysis is a work in progress and results might still change.

Data was taken from a test beam at the DESY II test beam facility (area 22 beam energy 4 GeV) carried out in October 2023.

Another alignment, systematic checking of various cuts, is still being carried out.

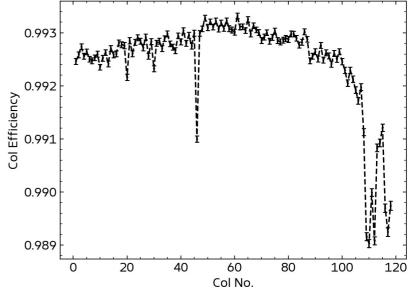
Efficiency

Efficiency = Tracks with an Associated DUT Hit
Tracks that intersect the DUT



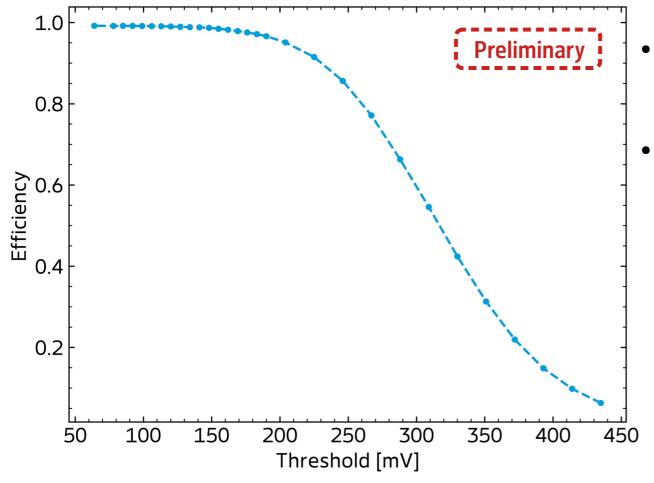
* Statstical efficiency

At a bias of 85 V & a threshold of 57 mV Efficiency of 99.204 ± 0.008 %



Efficiency vs Threshold

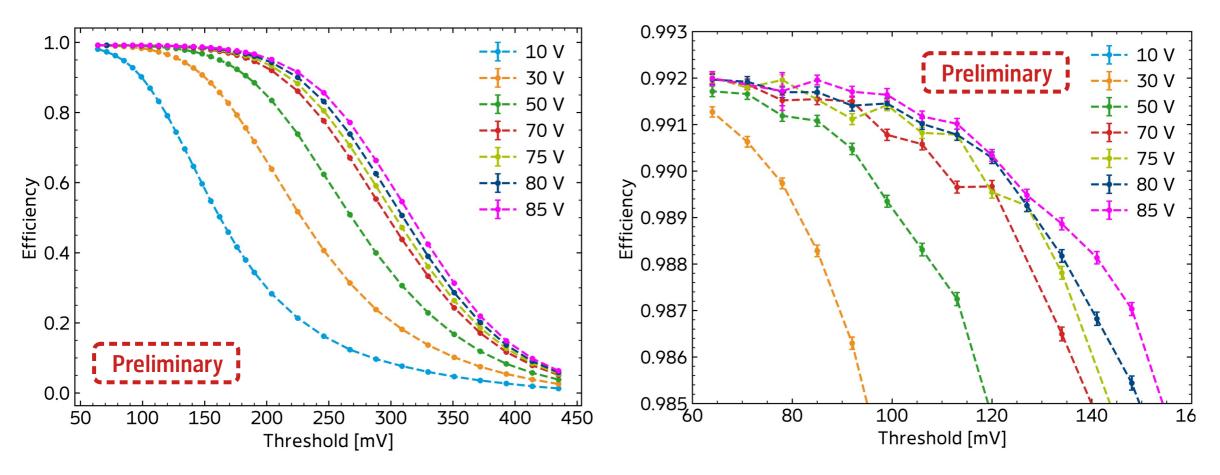
Efficiency changes with respect to threshold of pixel comparator



- Greater the plateau →
 Greater the suitable operating region
- Could not decrease threshold further Started to be effected by noise

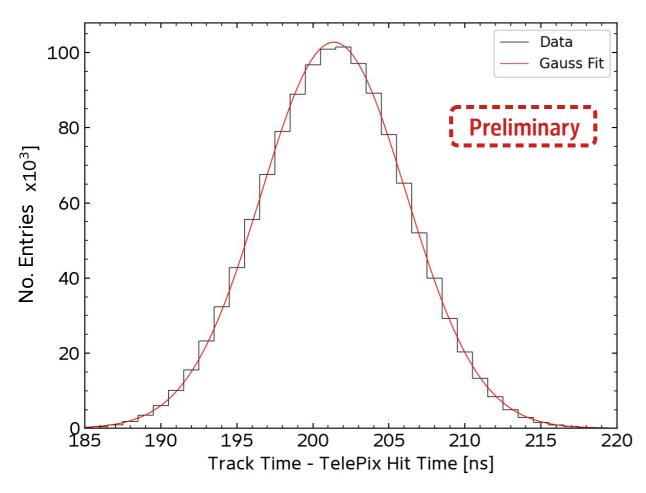
Bias is at 85 V

Efficiency vs Threshold for Different Voltages



Higher bias voltage → Greater depletion region → More charge collected

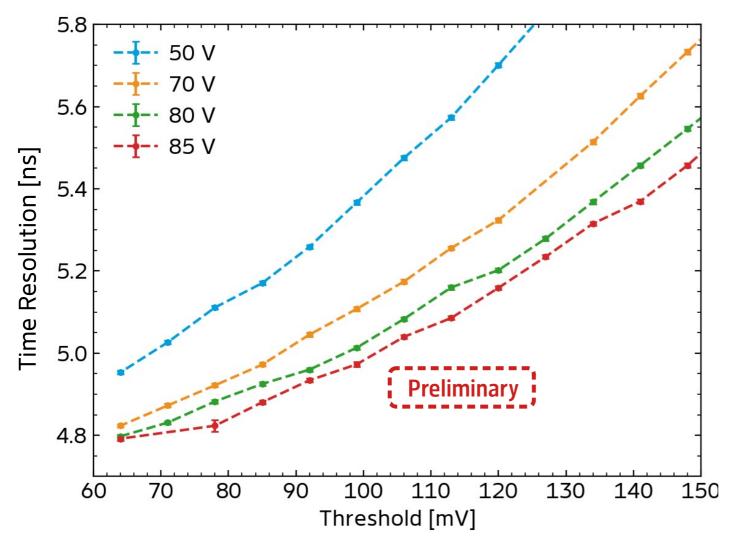
Timing Resolution Ideal Case



Time resolution taken as the σ of a Gaussian fit of the time residual

At a bias voltage of 85 V and a threshold of 57 mV a time resolution of 4.781 ± 0.003 ns.

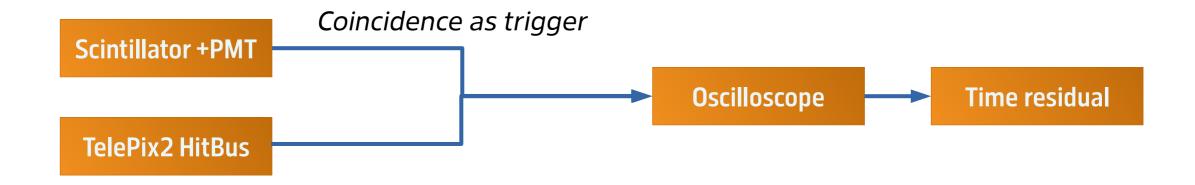
Timing Resolution with Threshold and Voltage



Still a benefit in time resolution with a reduction in threshold

HitBus Measurements Method

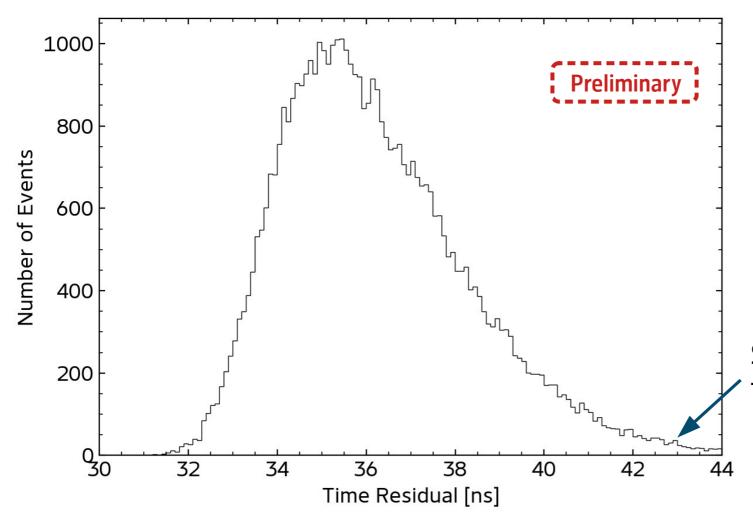
HitBus = Fast trigger output



Time Residual = Time at half maximum of scintillator – Time at half maximum of TelePix Hitbus

Hitbus Measurements

Result



Deviations from the standard Gauss distribution yet to be understood.

Preliminary measurements show an RMS of ≈ 2 ns

Taken with at a bias of 85 V and threshold of 64 mV

Slight background from imperfect triggering scheme

Conclusion

TelePix2 currently being used by users!

- Working ROI trigger
- Hitbus time resolution of ≈ 2 ns
- Efficiency 99.204 ± 0.008 %
- Uncorrected time resolution 4.781 ± 0.003 ns



The measurements leading to these results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF)

Thank you for listening!

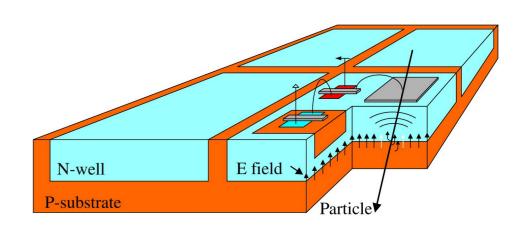
Questions?

High-Voltage Monolithic Active Pixel Sensors HV-MAPS

- Hybrid sensors bump bond a separate readout and sensor chip together
 - Can be costly to manufacture and have a high material budget
- Monolithic sensors integrate readout and sensor onto one chip:
 - But charge collection via diffusion → too slow for high rate applications

HV-MAPS embed readout inside pixel electrode

- Higher biasing voltage → collection via drift (faster)
- Can result in improved:
 - → Signal amplitude
 - → Charge collection speed
 - → Radiation tolerance



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Beam Telescopes at DESY II Testbeam facility

Most requested infrastructure by users (82% in 2022)

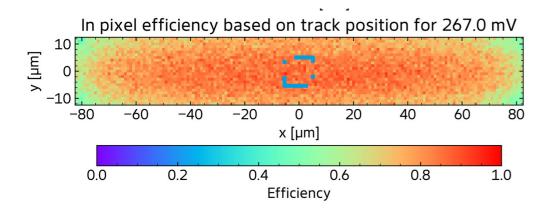
2 different types installed at desy **EUDET-Type** (TB21 & TB24) and **Adenium** (TB22)

	EUDET-Type	Adenium
Sensor	Mimosa26	Alpide
Active Area	2 x 1 cm	3 x 1.5 cm
Pixel Pitch	18.4 x 18.4 µm	29.24 x 26.88 μm
Read Out Time	> 115 µs	10 µs

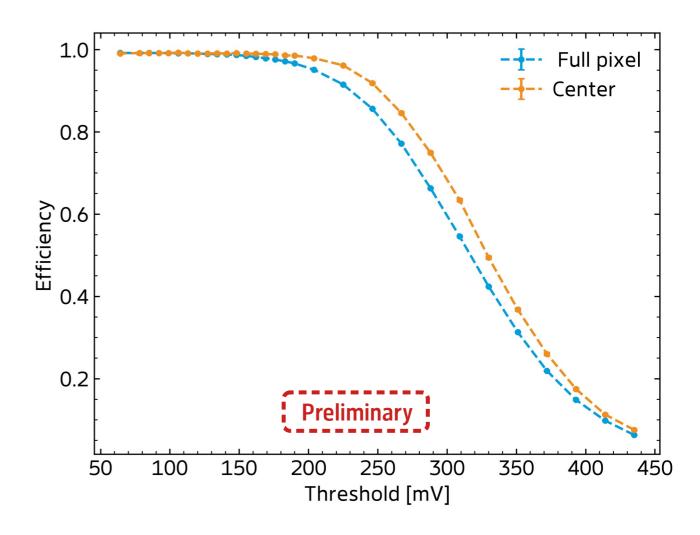
In Pixel Efficiency

Full Pixel and Center of Pixel Comparison

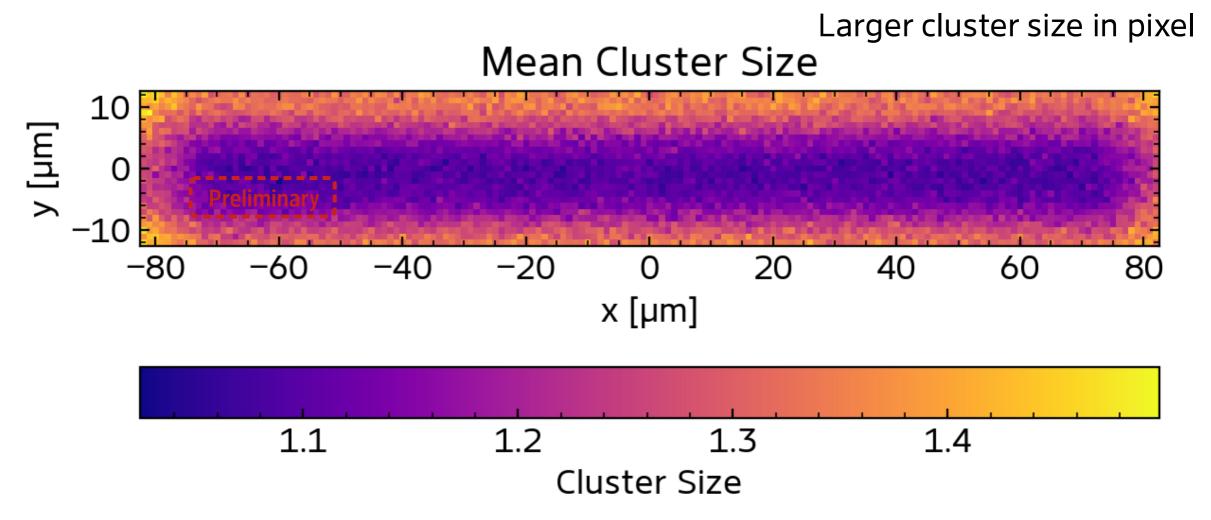
• Efficiency in the center 10 x 10 μm in each pixel calculated



- Larger plateau when looking at center of each pixel only
- Bias of 85V



In-Pixel Mean ClusterSize



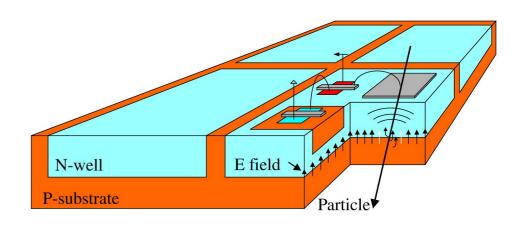
Bias 85 V and threshold 57 mV

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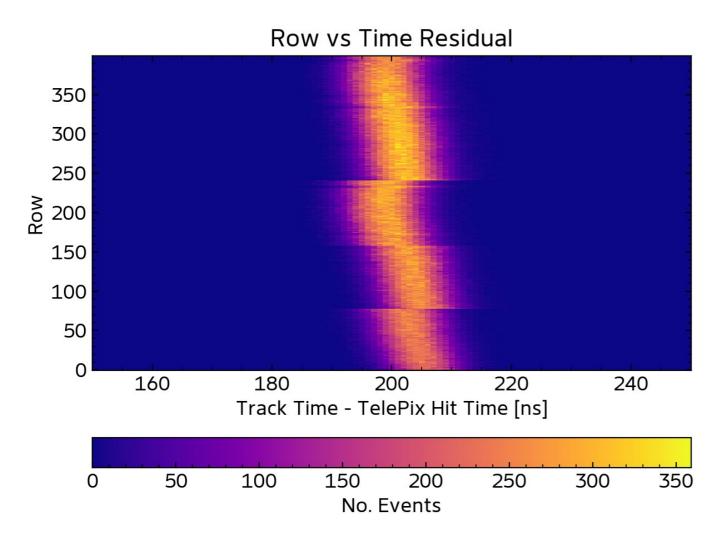
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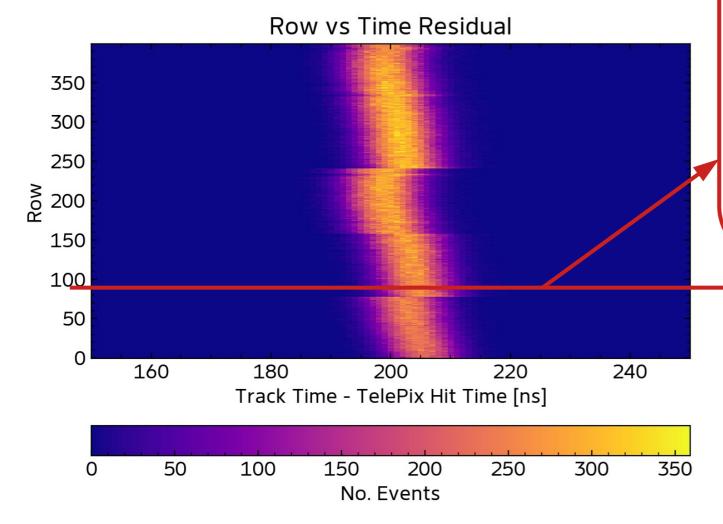






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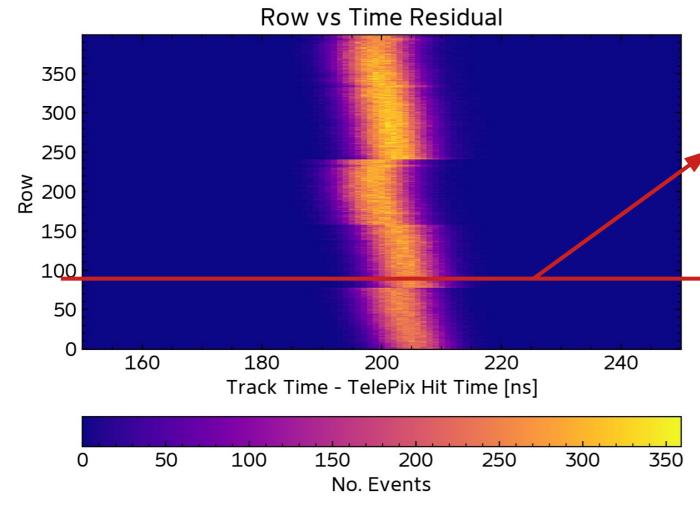
Time Residual Corrections



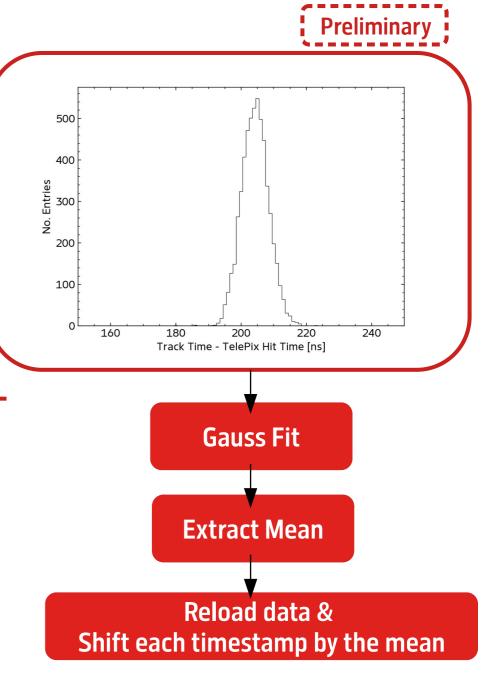
Track Time - TelePix Hit Time [ns]

Bias 85 V and threshold 57 mV

Time Residual Corrections

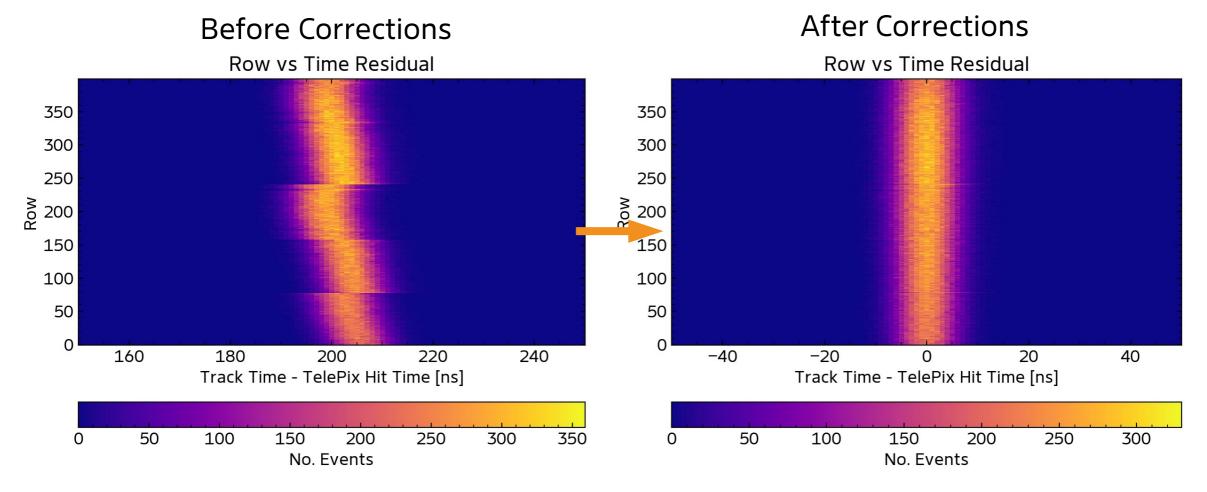


Bias 85 V and threshold 57 mV





Time Residual Corrections



This must be done offline

And requires processing the data twice

Bias 85 V and threshold 57 mV